

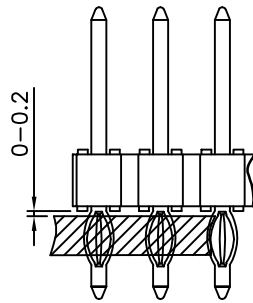
PRODUCT NUMBER
93690-YXX-XXLF

PLATING, SEE TABLE

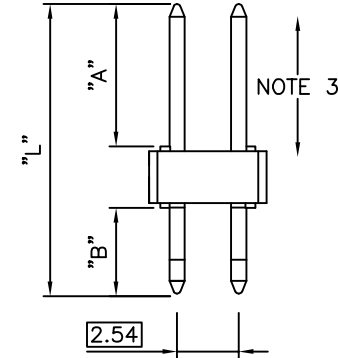
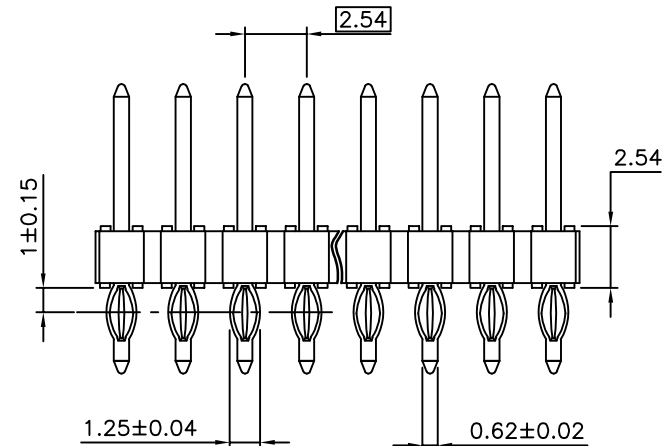
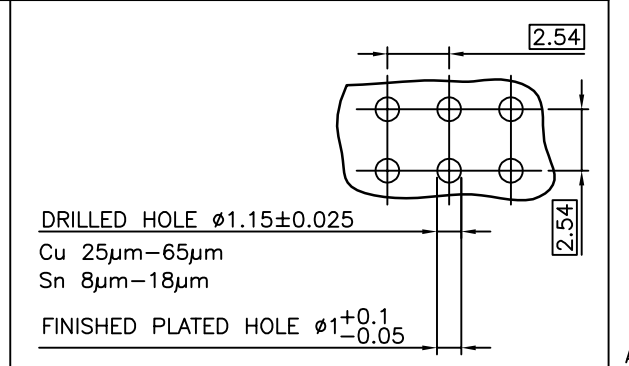
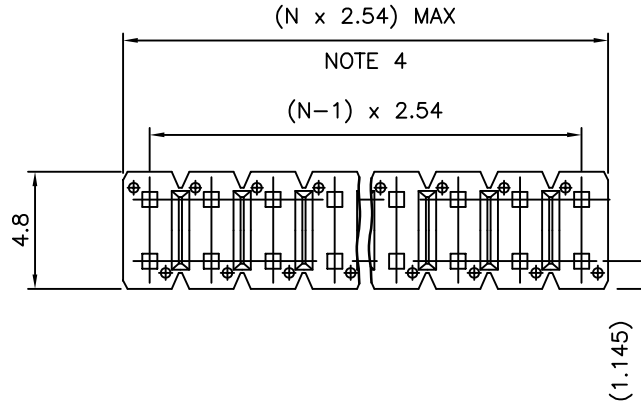
LEAD FREE
SEE NOTE 6 & 7

TOTAL NB OF POS
04 TO 72

PIN STYLE	DIM "A" REF	DIM "B" ±0.3	DIM "L" ±0.15
01	7.50	4.50	14.78
02	10.14	4.50	17.40
03	5.80	4.50	12.83
04	14.80	4.75	22.15
05	8.30	4.50	15.44
06	6.80	3.60	12.90
07	6.70	3.40	12.62
08	5.20	3.40	11.10
09	8.30	3.60	14.40
10	9.20	3.35	15.09
11	4.00	3.40	9.94



RECOMMENDED
POSITION ON THE PCB



NOTES:

- HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0 COLOR: BLACK
- PIN MATERIAL : COPPER ALLOY
- 9N MIN RETENTION IN EITHER DIRECTION
- TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS PER ROW, N x 2.54 = 20.32mm
- PACKAGING POLYBAGS OR BLIBOX
- LEAD FREE CONNECTOR
- "LF" MEANS THAT THE PRODUCT IS RoHS COMPLIANT THEN MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-47-0004

93690-7XX-XXLF	GOLD FLASH OVER 1.27µm Ni MIN	1.0µm TIN OVER 1.27µm Ni MIN
93690-5XX-XXLF ONLY AVAILABLE UPON REQUEST	0.25µm GOLD/GXT OVER 1.27µm Ni MIN	1.0µm TIN OVER 1.27µm Ni MIN
93690-4XX-XXLF	3.05µm TIN OVER 1.27µm Ni MIN	
93690-1XX-XXLF	0.76µm GOLD/GXT OVER 1.27µm Ni MIN	1.0µm TIN OVER 1.27µm Ni MIN
PLATING	CONTACT AREA	PRESS FIT TAIL AREA

mat'l. code		surface		tolerance		projection	product family	
SEE NOTE		ISO 1302	ISO 406	ISO 1101	ISO 1101	mm	BERGSTIK	
ltr	ecn no	dr	date		tolerances unless otherwise specified		title	
R	B-18988	LMU	14.10.06		angles	linear	HDR PRESS FIT DOUBLE ROW	
S	F-22590	AMA	15.11.23				dwg no	
T	F-47108	DDE	23.01.25				sheet 1 of 1	
			dr	MULIN.L		scale 5:1	size	
			enrg	COMPAGNON J			93690	
N	B16804	JCO	14.01.21		chr	NIZZI.P	A3	
P	B-17404	JCO	14.04.07		appd	JM.C	type	
sheet	revision						CUSTOMER Drawing	
index	sheet							